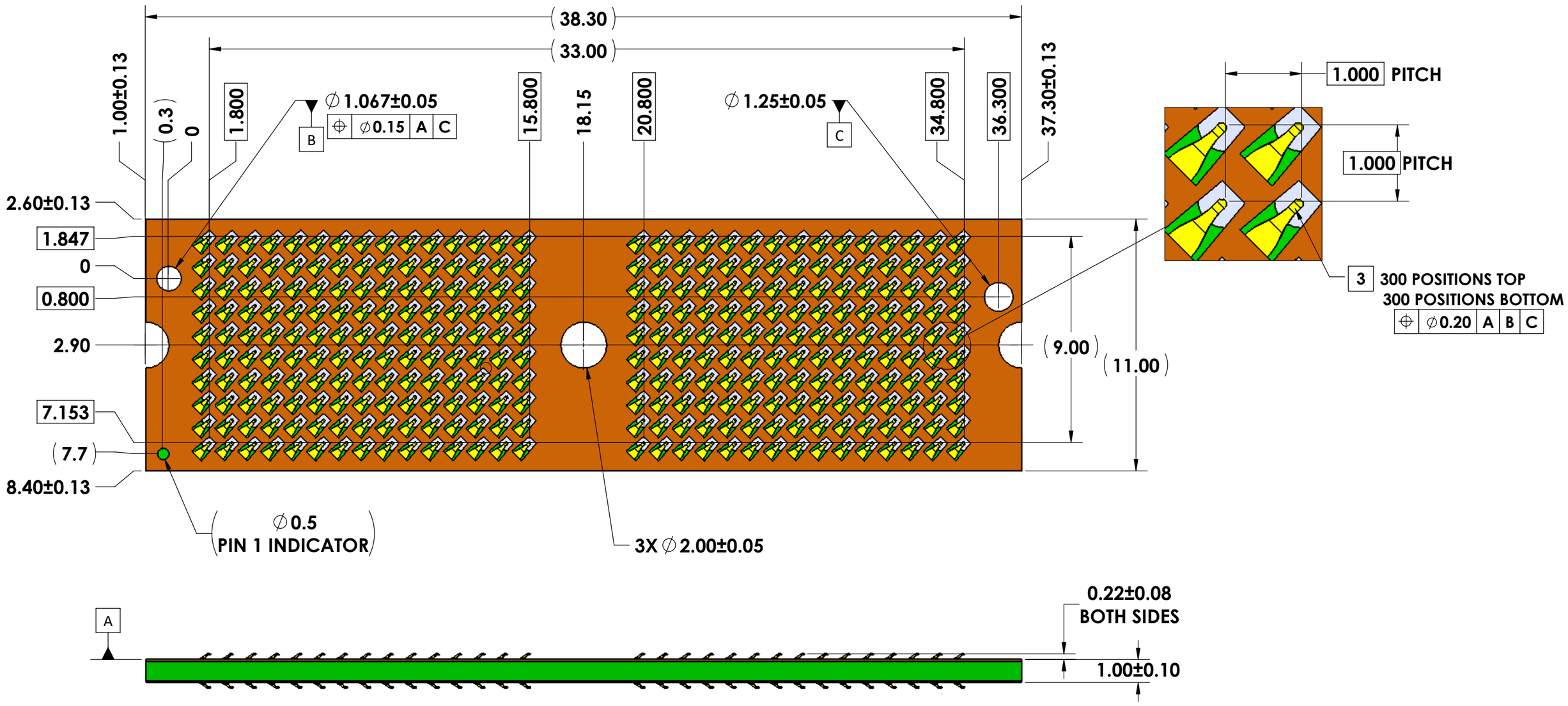
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REVISIONS				
REV	ECO	DESCRIPTION	DATE	DRAWN BY
1	0000	INITIAL RELEASE	10-01-2026	TAN



NOTES (UNLESS OTHERWISE SPECIFIED):

1. INTERPRET DRAWING PER ASME Y14.5-2018.
2. COMPLIANT WITH RoHS DIRECTIVE 2011/65/EU AND REACH.
3. CENTER MARKS OF CONTACT POSITIONS ARE FOR COMPRESSED STATE.

REF: Z-RAY P/N ZA1-30-2-1.00-Z-10

neoconix
4020 MOORPARK AVE. #108
SAN JOSE, CA 95117 USA
TEL: 408-530-9393 FAX: 408-530-9383

DIMENSIONS ARE IN MM [INCH]
.X ± 0.13 [.005]
.XX ± 0.08 [.003]
.XXX ± 0.025 [.001]
ANGLE: NO DEC ±2 DEGREE
.X ±
.XX ±
THIRD ANGLE

MATERIAL: SEE NOTES	
FINISH: SEE NOTES	
DRAWN BY: TAN NGUYEN	10-01-2026
CHECKED BY:	
ENGR APPR:	
MFG APPR:	
QA APPR:	

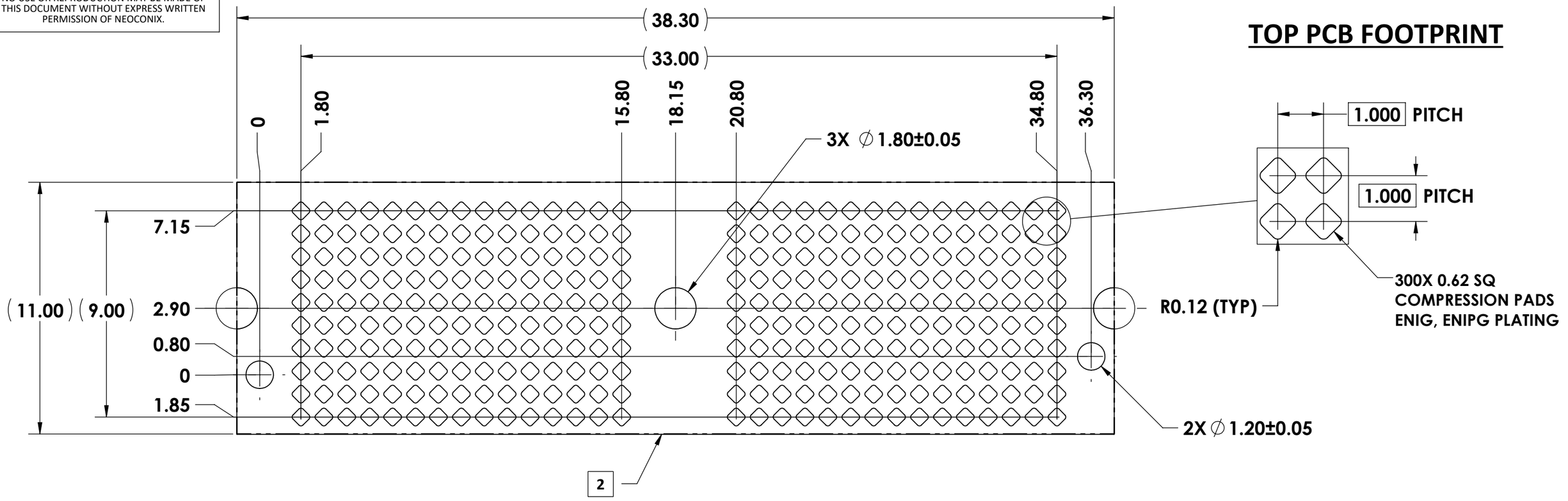
TITLE: 300 POSITIONS INTERPOSER LGA-LGA PCBEAM (1.0mm PITCH)

SIZE	DWG NUMBER:	REV
B+	SPZ-D300LA	1

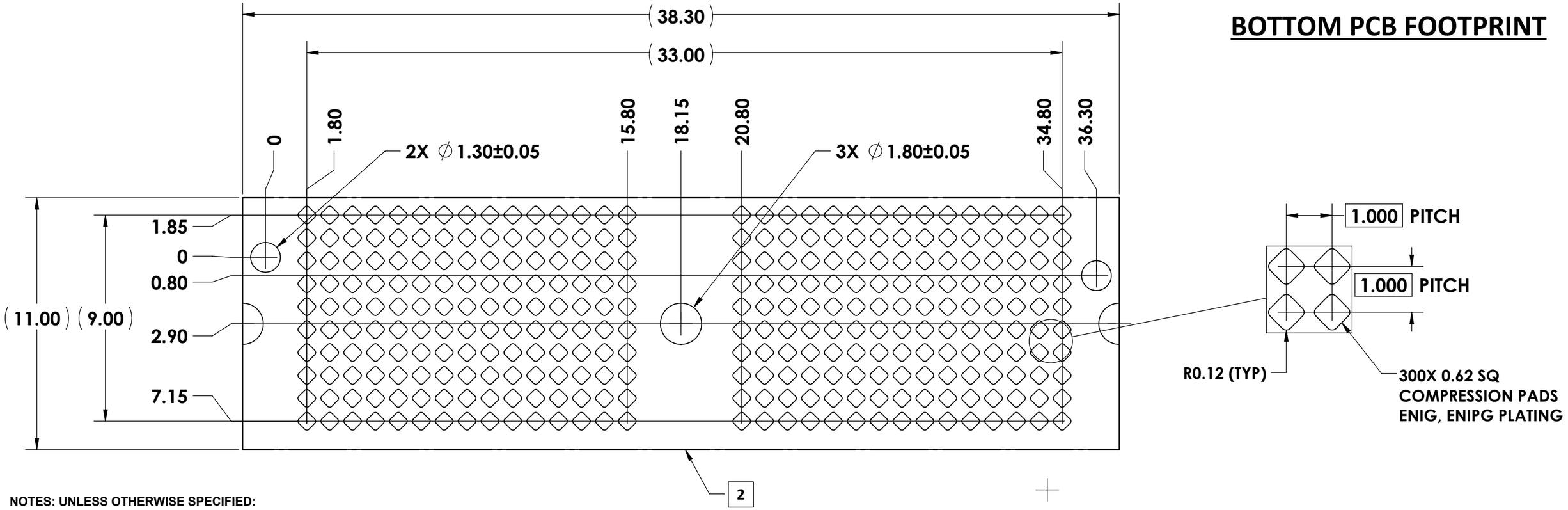
SCALE: 5:1 SHEET 1 OF 2

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TOP PCB FOOTPRINT



BOTTOM PCB FOOTPRINT



NOTES: UNLESS OTHERWISE SPECIFIED:

1. VIAS IN PAD AREA MUST BE FILLED, PLATED AND PLANARIZED WITH 25UM MAX DIMPLE.
2. INTERPOSER OUTLINE; NO COMPONENTS ALLOWED WITHIN THIS AREA.
3. IF SOLDERMASK IS APPLIED IN THE ARRAY AREA IT SHALL NOT PROTRUDE ABOVE THE PLANE OF THE CONTACT PAD SURFACE.

necconix
4020 MOORPARK AVE. #108
SAN JOSE, CA 95117 USA
TEL: 408-530-9393 FAX: 408-530-9383

DIMENSIONS ARE IN MM [INCH]
.X ± 0.13 [.005]
.XX ± 0.08 [.003]
.XXX ± 0.025 [.001]
ANGLE: NO DEC ±2 DEGREE
.X ±
.XX ±
THIRD ANGLE

MATERIAL: SEE NOTES	
FINISH: SEE NOTES	
DRAWN BY: TAN NGUYEN	10-01-2026
CHECKED BY:	
ENGR APPR:	
MFG APPR:	
QA APPR:	

TITLE: RECOMMEND PCB FOOTPRINT

SIZE	DWG NUMBER:	REV
B+	SPZ-D300LA-PCB	1

SCALE: 2:1 SHEET 2 OF 2